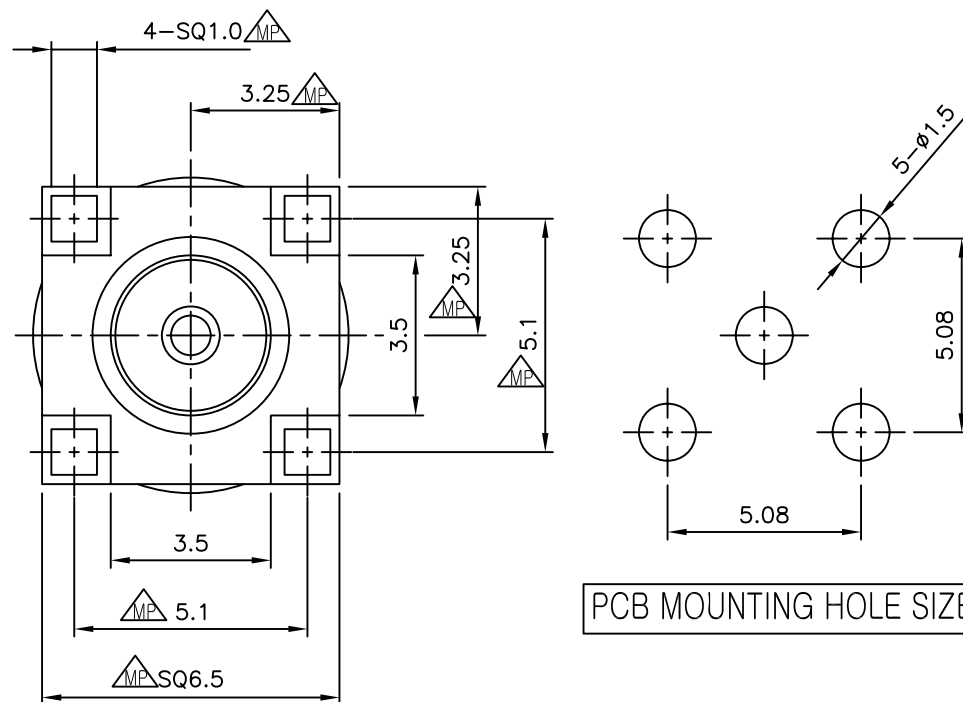
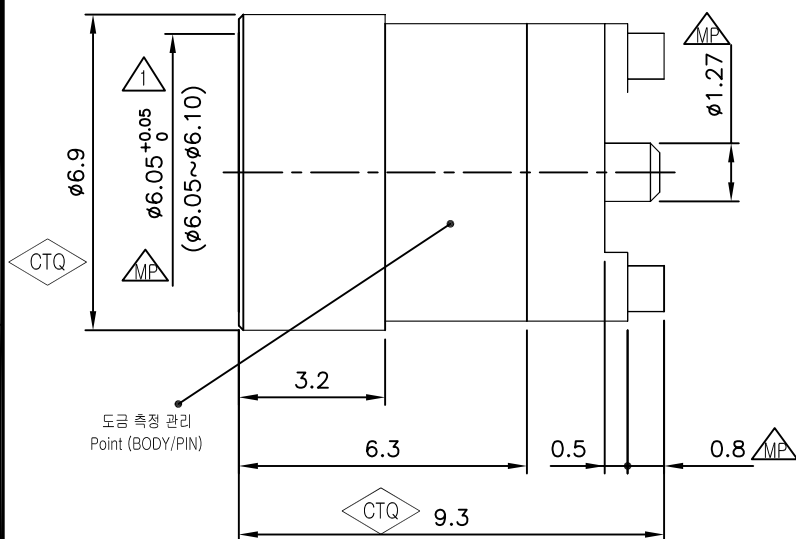


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	H.J.LEE	I.C.KIM	2015.03.18.
1	[설번No.201506-0021]내경부 관리 치수 변경(CTQ-> MP Point로 변경) ($\phi 6.15 \pm 0.1 \rightarrow \phi 6.05 \pm 0.05/0$)	H.J.LEE	I.C.KIM	2015.06.23.



NOTE

1. 도금 사양

-BODY : 하지 Ni ($2\mu\text{m} \sim 10\mu\text{m}$)

Gold ($0.06\mu\text{m} \sim 2\mu\text{m}$)

-CONTACT : 하지 Ni ($2\mu\text{m} \sim 10\mu\text{m}$)

Gold ($0.06\mu\text{m} \sim 2\mu\text{m}$)

-JACK : 하지 Ni ($2\mu\text{m} \sim 10\mu\text{m}$)

Gold ($0.06\mu\text{m} \sim 2\mu\text{m}$)

2. 기재한 관리 공차외에 치수는 일반공차 적용

4	JACK	1	MBsBD	Note 참조	DJA00159-5/6
3	INSULATOR	1	TEFLON		DIN02179-N/1
2	CONTACT	1	BeCu	Note 참조	DCT03443-5/1
1	BODY	1	MBsBD	Note 참조	DBD03911-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2015. 06. 23.			 KJ COMTECH CO.,LTD.	RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017		
	Angle	APPROVED BY	I.C.KIM					
MATERIAL	_____	CHECKED BY	S.M.LEE		TITLE			SMBL50 PCB JS-4R
		DRAWN BY	H.J.LEE					
FINISH	_____	SCALE	6/1	UNIT		A4	DWG NO.	CN03313-7/6
							REVISION	1